

**Response Under 37 CFR 1.116**

**Expedited Procedure**

**Examining Group 1700**

Application No. 09/743,155

Paper Dated: November 10, 2006

In Reply to USPTO Correspondence of September 21, 2006

Attorney Docket No. 3135-010012

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

Claims 1–12 (Cancelled).

Claim 13 (Currently Amended): A mould for encapsulating electronic components mounted on a carrier, comprising:

at least two mould parts displaceable relative to each other, at least one of which is provided with a recess for holding the electronic components and to be filled with encapsulating material, and

feed means for filling the recess with encapsulating material,

wherein at least a lower mould part of the mould parts is provided with a runner which connects on one side to a wall of the lower mould part co-defining a mould cavity and connects on the other side to a side of the lower mould part remote from the mould cavity,

wherein the lower mould part comprises a flat support surface provided with plural runners arranged in patterns corresponding with locations where the recess in the at least one mould part is formed, the plural—~~suction~~ runners adapted to extract gasses therethrough to adhere the carrier in a flat position at multiple positions to the lower mould part.

Claim 14 (Previously Presented): The mould as claimed in claim 13, wherein a plurality of runners connecting onto the wall defining the mould cavity are in mutual communication and are connected to a single runner which connects onto a side of the lower mould part remote from the mould cavity.

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**Claim 15 (Previously Presented):** The mould as claimed in claim 13, wherein the runner debouches in a wall defining a mould cavity, which wall is screened from a feed opening for encapsulating material by a carrier when encapsulating material is fed to the mould.

**Claim 16 (Previously Presented):** The mould as claimed in claim 13, wherein apertures are arranged in the wall of a lower mould part in patterns.

**Claim 17 (Previously Presented):** The mould as claimed in claim 13, wherein the lower mould part is provided with at least one aligning edge for positioning a carrier relative to the lower mould part.

**Claim 18 (Previously Presented):** An encapsulating device for encapsulating electronic components mounted on a carrier, comprising:

a mould as claimed in claim 13,

drive means for positioning and causing the mould parts to move relative to each other,

feed means for encapsulating material, and

a fan connecting onto the side of the runner remote from the mould cavity.

**Claim 19 (Currently Amended):** A method for encapsulating electronic components mounted on a carrier, using a mould with a lower mould part and an upper mould part defining a mould cavity, the method comprising the steps of:

A) positioning at least one carrier relative to the lower mould part, the lower mould part comprising a flat support surface provided with plural runners arranged in patterns corresponding with locations where a recess in the lower mould part is formed, the plural ~~suction~~ runners adapted to extract gasses therethrough to adhere the carrier in a flat position at multiple positions to the lower mould part,

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B) closing the mould by moving the lower mould part and ~~an~~the upper mould part towards each other,

C) feeding encapsulating material to the part of the mould cavity left clear by the carrier, and

D) opening the upper and lower mould parts and removing the carrier with encapsulating material arranged thereon, wherein during step D) an overpressure is applied in the plural runners which overpressure releases the encapsulated electronic components from the lower mould part.

Claim 20 (Previously Presented): The method as claimed in claim 19, wherein after step A) and during step B) an underpressure is applied in the plural runners, whereby the carrier is sucked to the lower mould part.